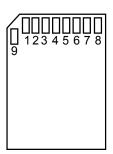
# **Description**

TS64MSDC is a 64MB Secure Digital Card. It is non-volatile, which means no external power is required to retain the information stored on it. Besides, it is also a solid-state device that without moving parts to skip or break down. TS64MSDC can offer an incredible combination of fast data transfer, great flexibility, excellent security and incredibly small size.

## **Placement**





Front

**Back** 

#### **Features**

• Storage Capacity: 64MB

• Operating Voltage: 2.7 ~ 3.6V

• Operating Temperature: -25 ~ 85°C

• Data Transfer Rate: Average 2MB/s

• Durability: 10,000 insertion/removal cycles

· Mechanical Write Protection Switch

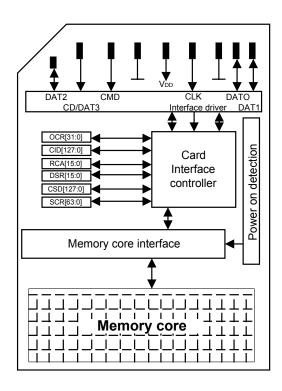
• SD Host allows MultiMediaCard upward compatibility

• Form Factor: 24mm x 32mm x 2.1mm

#### **Pin Definition**

Pin No.	Name	Туре	Description
1	CD/DA	I/O/PP <sup>3</sup>	Card Detect/Data Line [Bit3]
2	CMD	PP	Command/Response
3	V <sub>SS1</sub>	S	Supply voltage ground
4	$V_{DD}$	S	Supply voltage
5	CLK	I	Clock
6	$V_{SS2}$	S	Supply voltage ground
7	DAT0	I/O/PP	Data Line [Bit0]
8	DAT1	I/O/PP	Data Line [Bit1]
9	DAT2	I/O/PP	Data Line [Bit2]

### **Architecture**



## **Bus Operating Conditions**

#### General

Parameter	Symbol	Min.	Max.	Unit	Remark
Peak voltage on all lines		-0.3	VDD+0.3	V	
All Inputs					
Input Leakage Current		-10	10	μΑ	
All Outputs					
Output Leakage Current		-10	10	μΑ	

# Power Supply Voltage

Parameter	Symbol	Min.	Max.	Unit	Remark
Supply voltage	$V_{DD}$	2.0	3.6	V	CMD0, 15,55,ACMD41
					commands
Supply voltage specified in OCR register					Except CMD0, 15,55,
					ACMD41 commands
Supply voltage differentials (V <sub>SS1</sub> , V <sub>SS2</sub> )		-0.3	0.3	V	
Power up time			250	ms	From 0v to V <sub>DD</sub> Min.

Note. The current consumption of any card during the power-up procedure must not exceed 10 mA.

## Bus Signal Line Load

The total capacitance  $C_L$  the CLK line of the SD Memory Card bus is the sum of the bus master capacitance  $C_{HOST}$ , the bus capacitance  $C_{BUS}$  itself and the capacitance  $C_{CARD}$  of each card connected to this line:  $C_L = C_{HOST} + C_{BUS} + N^*C_{CARD}$ 

Where N is the number of connected cards. Requiring the sum of the host and bus capacitances not to exceed 30 pF for up to 10 cards, and 40 pF for up to 30 cards, the following values must not be exceeded:

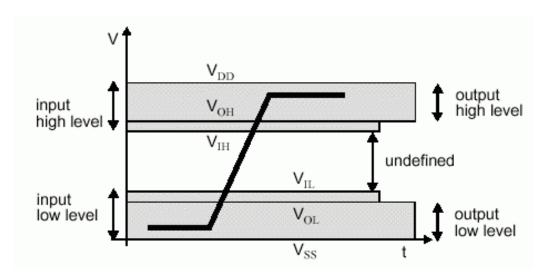
Parameter	Symbol	Min.	Max.	Unit	Remark
Bus signal line capacitance	$C_L$		100	pF	$f_{PP} \le 20$ MHz, 7 cards
Single card capacitance	C <sub>CARD</sub>		10	pF	
Maximum signal line inductance			16	nΗ	$f_{PP} \le 20 \text{ MHz}$
Pull-up resistance inside card (pin1)	R <sub>DAT3</sub>	10	90	KΩ	May be used for card
					detection

Note that the total capacitance of CMD and DAT lines will be consist of  $C_{\text{HOST}}$ ,  $C_{\text{BUS}}$  and one  $C_{\text{CARD}}$  only since they are connected separately to the SD Memory Card host.

Parameter	Symbol	Min.	Max.	Unit	Remark
Pull-up resistance	$R_{CMD}, R_{DAT}$	10	100	$K\Omega$	To prevent bus floating
Bus signal line capacitance	$C_L$		250	pF	f <sub>PP</sub> ≤ 5 MHz, 21 cards

## • Bus Signal Levels

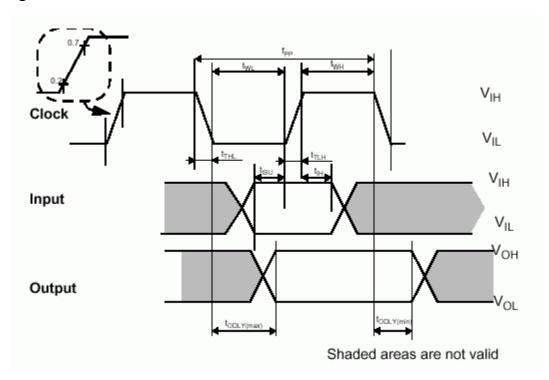
As the bus can be supplied with a variable supply voltage, all signal levels are related to the supply voltage.



To meet the requirements of the JEDEC specification JESD8-1A, the card input and output voltages shall be within the following specified ranges for any  $V_{DD}$  of the allowed voltage range:

Parameter	Symbol	Min.	Max.	Unit	Remark
Output HIGH voltage	$V_{OH}$	0.75* V <sub>DD</sub>		V	I <sub>OH</sub> = -100 μA @V <sub>DD</sub> min
Output LOW voltage	$V_{OL}$		0.125* V <sub>DD</sub>	V	I <sub>OL</sub> = -100 μA @V <sub>DD</sub> min
Input HIGH voltage	V <sub>IH</sub>	0.625* V <sub>DD</sub>	V <sub>DD</sub> + 0.3	V	
Input LOW voltage	$V_{IL}$	$V_{SS} - 0.3$	0.25* V <sub>DD</sub>	V	

# • Bus Timing



Parameter	Symbol	Min	Max.	Unit	Remark	
Clock CLK (All values are referred to min $(V_{IH})$ and max $(V_{IL})$						
Clock frequency Data Transfer Mode	$f_{PP}$	0	25	MHz	C <sub>L</sub> ≤ 100 pF, (7 cards)	
Clock frequency Identification Mode	$f_{OD}$	0	400	KHz	C <sub>L</sub> ≤ 250 pF, (21 cards)	
(The low freq. is required for MultiMediaCard						
compatibility.)						
Clock low time	t <sub>WL</sub>	10		ns	$C_L \le 100 \text{ pF, } (7 \text{ cards})$	
		50		ns	$C_L \le 250 \text{ pF, (21 cards)}$	
Clock high time	t <sub>WH</sub>	10		ns	C <sub>L</sub> ≤ 100 pF, (7 cards)	
		50		ns	C <sub>L</sub> ≤ 250 pF, (21 cards)	
Clock rise time	t <sub>TLH</sub>		10	ns	C <sub>L</sub> ≤ 100 pF, (7 cards)	
			50	ns	$C_L \le 250$ pF, (21 cards)	
Clock fall time	t <sub>THL</sub>		10	ns	C <sub>L</sub> ≤ 100 pF, (7 cards)	
			50	ns	C <sub>L</sub> ≤ 250 pF, (21 cards)	
Inputs CMD, DAT (referenced to CLK)						
Input set-up time	t <sub>ISU</sub>	5		ns	$C_L \le 25 \text{ pF}, (1 \text{ cards})$	
Input hold time	t <sub>IH</sub>	5		ns	$C_L \le 25 \text{ pF, (1 cards)}$	
Outputs CMD, DAT (referenced to CLK)						
Output Delay time	t <sub>ODLY</sub>	0	14	ns	$C_L \le 25 \text{ pF}, (1 \text{ cards})$	

# **Reliability and Durability**

Temperature	Operation: -25°C / 85°C (Target spec)
	Storage: -40°C (168h) / 85°C (500h)
	Junction temperature: max. 95°C
Moisture and corrosion	Operation: 25°C / 95% rel. humidity
	Storage: 40°C / 93% rel. hum./500h
	Salt Water Spray: 3% NaCl/35C; 24h acc. MIL STD Method 1009
Durability	10.000 mating cycles; test procedure: tbd.
Bending	t.b.d
Torque	t.b.d
Drop test	1.5m free fall
UV light exposure	UV: 200nm, 15Ws/cm² according to ISO 7816-1
Visual inspection	No warp page; no mold skin; complete form; no cavities surface smoothness <=
Shape and form	-0.1 mm/cm² within contour; no cracks; no pollution (fat, oil dust, etc.)
Minimum moving force of WP witch	40gf (Ensures that the WP switch will not slide while it is inserted to the connector.)
WP Switch cycles	t.b.d

Above technical information is based on industry standard data and tested to be reliable. However, Transcend makes no warranty, either expressed or implied, as to its accuracy and assumes no liability in connection with the use of this product. Transcend reserves the right to make changes in specifications at any time without prior notice.